

RELIABILITY REPORT  
FOR  
REF01HSA+  
PLASTIC ENCAPSULATED DEVICES

August 2, 2013

**MAXIM INTEGRATED**

160 RIO ROBLES  
SAN JOSE, CA 95134

<b>Approved by</b>
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Quality Assurance
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## Conclusion

The REF01HSA+ successfully meets the quality and reliability standards required of all Maxim Integrated products. In addition, Maxim Integrated's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim Integrated's quality and reliability standards.

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### I. Device Description

#### A. General

The REF01/REF02 are industry-standard precision voltage references. The stable 10V output of the REF01 can be adjusted over a  $\pm 6\%$  range with minimal effect on temperature stability. The 5V output REF02 can also be adjusted over a  $\pm 6\%$  range. The 10V REF01 has a single-supply operation over an input voltage range of 13V to 33V, while the 5V REF02 has a single-supply operation over an input voltage range of 7V to 33V. Both devices offer a low-current drain of 1mA. The REF02 also provides a TEMP pin whose output voltage varies linearly with temperature, making this device suitable for a wide variety of temperature-sensing and control applications. For new designs, refer to the [MAX6035](#) or [MAX6143](#) data sheets.

## II. Manufacturing Information

A. Description/Function:	+5V, +10V Precision Voltage References
B. Process:	S3
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Malaysia, Philippines, Thailand
F. Date of Initial Production:	Pre 1997

## III. Packaging Information

A. Package Type:	8-pin SOIC (N)
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	84-1Imisr4
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-0923
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	170°C/W
K. Single Layer Theta Jc:	40°C/W
L. Multi Layer Theta Ja:	132°C/W
M. Multi Layer Theta Jc:	38°C/W

## IV. Die Information

A. Dimensions:	65 X 120 mils
B. Passivation:	Si <sub>3</sub> N <sub>4</sub> /SiO <sub>2</sub> (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	3.0 microns (as drawn)
F. Minimum Metal Spacing:	3.0 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO <sub>2</sub>
I. Die Separation Method:	Wafer Saw

## V. Quality Assurance Information

- A. Quality Assurance Contacts: Richard Aburano (Manager, Reliability Engineering)  
Don Lipps (Manager, Reliability Engineering)  
Bryan Preeshl (Vice President of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.  
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

## VI. Reliability Evaluation

### A. Accelerated Life Test

The results of the 135C biased (static) life test are shown in Table 1. Using these results, the Failure Rate ( $\lambda$ ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 400 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 2.7 \times 10^{-9}$$

$$\lambda = 2.7 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim Integrated's reliability monitor program. Maxim Integrated performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maximintegrated.com/qa/reliability/monitor>. Cumulative monitor data for the S3 Process results in a FIT Rate of 0.03 @ 25C and 0.5 @ 55C (0.8 eV, 60% UCL)

### B. E.S.D. and Latch-Up Testing (lot GHACCX002A, D/C 9644)

The RF36-4 die type has been found to have all pins able to withstand a HBM transient pulse of +/-1500V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-100mA.

**Table 1**  
Reliability Evaluation Test Results

## REF01HSA+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
<b>Static Life Test</b> (Note 1)	Ta = 135°C	DC Parameters & functionality	80	0	MHACBI008B, D/C 9348
	Biased		80	0	MHACRC041C, D/C 9003
	Time = 192 hrs.		80	0	MHACRB039A, D/C 8936
			80	0	MHACRB037B, D/C 8938
			80	0	MHACRY026C, D/C 8931

Note 1: Life Test Data may represent plastic DIP qualification lots.